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Attorney Docket No. 2003P01973WOUS

CERTIFICATE OF MAILING UNDER 37 CFR 1.8

Serial No.: 10/583,634
Filing Date: 06/20/2006
Applicant: Bruno Reiter et al
Title: THICK-FILM FLUID HEATER AND CONTINUOUS HEATING DEVICE
Date of Deposit: July 10, 2006
Type of Document(s): Certificate of Mailing (1 page);
Supplemental Information Disclosure Statement (10 pages)
Return postcard.

CERTIFICATE OF MAILING UNDER 37 C.F.R. Section 1.8

I hereby certify that this paper, including all enclosures referred to herein, is being deposited with the United States Postal Service as first-class mail, postage pre-paid, in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on:

July 10, 2006

Date of Deposit

Russell W. Warnock

Name of Person Signing

Signature

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UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Bruno Reiter et al

Application Number: 10/583,634

Filing Date: 06/20/2006

Group Art Unit:

Examiner:

Title: THICK-FILM FLUID HEATER AND CONTINUOUS
HEATING DEVICE

Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Sir:

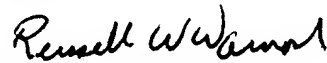
In accordance with 37 C.F.R. 1.98, I am submitting a completed "SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT BY APPLICANTS" (*Form PTO/SB/08A*) with patents and/or publications as delineated therein attached.

EP 0 686 815 discloses the heating element (11) has a flow pipe (120 for the fluid medium (19), heated on the outside by a resistance heating element (14) in the form of a wound band. The heating is controlled by an electronic temp. regulation circuit (28), mounted on a printed circuit board (23) on the outside of the pipe, coupled to a temp. sensor (26) within the pipe. The semiconductor power components controlled by the temp. regulating circuit are thermically coupled to the flow pipe via a heat sink element (18), so that their waste heat is dissipated via the heated flow medium.

If no translation of pertinent portions of any foreign language patents or publications mentioned within the "SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT BY APPLICANTS" is included with the aforementioned copies of those applications, patents and/or publications, it is because no existing translation is readily available to the Applicants.

As per the Notice in 1273 OG 55 (August 5, 2003) no copies of any above-mentioned US patents and US patent application publications are submitted for this application which was filed after June 30, 2003.

Respectfully submitted

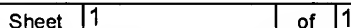


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Filing Date	06/20/2006
First Named Inventor	Bruno Reiter et al
Art Unit	
Examiner Name	
Attorney Docket Number	2003P01973WQUS

If you need assistance in completing the form, call 1-800-PTO-9199 (1-800-786-9199) and select option 2.